



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2016-01-07
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	IPD MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STB76NF75	TGD2*ED7HA62	A	SHENZHEN B/E	2016-01-07
Amount		UoM	Unit type	ST ECOPACK Grade
1380.00		mg	Each	ECOPACK1

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	245	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
SIP	10.2, 9.15, 4.5	2	GULL WING	
Comment	D2PAK			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	TGD2*ED7HA62					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	15.189	mg	supplier	die	Silicon (Si)	7440-21-3		14.696	mg	967538	10648
				supplier	metallization	Aluminium (Al)	7429-90-5		0.286	mg	18832	207
				supplier	Passivation	Silicon Oxide	7631-86-9		0.079	mg	5202	57
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.007	mg	461	5
				supplier	back side metallization	Gold (Au)	7440-57-5		0.021	mg	1383	15
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.100	mg	6585	72
Leadframe	Copper & its alloys	779.567	mg	supplier	alloy	Copper (Cu)	7440-50-8		777.537	mg	997396	563433
				supplier	alloy	Iron (Fe)	7439-89-6		0.358	mg	459	259
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.654	mg	839	474
				supplier	metallization	Nickel (Ni)	7440-02-0		1.012	mg	1298	733
				supplier	metallization	Phosphorus (P)	12185-10-3		0.006	mg	8	4
				supplier	metallization	Phosphorus (P)	12185-10-3		0.006	mg	8	4
Soft solder	Solder	13.625	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	13.012	mg	955009	9429
				supplier	solder	Silver (Ag)	7440-22-4		0.341	mg	25028	247
				supplier	solder	Tin (Sn)	7440-31-5		0.272	mg	19963	197
Bonding wires	Other inorganic materials	2.525	mg	supplier	wire	Aluminium (Al)	7429-90-5		2.524	mg	999683	1829
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	317	1
				supplier	mold compound	Silica, vitreous	60676-86-0		456.685	mg	806002	330931
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		39.662	mg	69999	28741
				supplier	mold compound	Phenol resin	9003-35-4		22.664	mg	40000	16423
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		33.996	mg	59999	24635
Encapsulation	Other Organic Materials	566.605	mg	supplier	mold compound	Antimony Trioxide	1309-64-4		6.799	mg	12000	4927
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		3.966	mg	7000	2874
				supplier	mold compound	Carbon black	1333-86-4		2.833	mg	5000	2053
				supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		39.662	mg	69999	28741
				supplier	mold compound	Phenol resin	9003-35-4		22.664	mg	40000	16423